

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT6354988

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
SATORU ENDO	10/06/2020
HITOSHI MAFUNE	10/05/2020
TAKASHI SUZUKI	10/06/2020
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	THREEBOND CO., LTD.
<b>Street Address:</b>	4-3-3 MINAMIOSAWA, HACHIOJI-SHI
<b>City:</b>	TOKYO
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	192-0398
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	17048335
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(212)661-8002
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	2126618000
<b>Email:</b>	info@Imiplaw.com
<b>Correspondent Name:</b>	SHINTARO YAMADA
<b>Address Line 1:</b>	30 BROAD ST. 21ST FLOOR
<b>Address Line 2:</b>	21ST FLOOR
<b>Address Line 4:</b>	NEW YORK, NEW YORK 10004
<b>ATTORNEY DOCKET NUMBER:</b>	HAT-1024
<b>NAME OF SUBMITTER:</b>	SHINTARO YAMADA
<b>SIGNATURE:</b>	/Shintaro Yamada/
<b>DATE SIGNED:</b>	10/17/2020
This document serves as an Oath/Declaration (37 CFR 1.63).	
<b>Total Attachments: 3</b>	
source=19P005US-Declaration-and-Assignment#page1.tif	
source=19P005US-Declaration-and-Assignment#page2.tif	



**DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN  
APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE**

<b>TITLE OF INVENTION</b>	<b>CONDUCTIVE SILICONE COMPOSITION AND CURED PRODUCT THEREOF</b>	
<p>As the below named inventor, I hereby declare that:</p> <p>This declaration is directed to:</p> <p><input checked="" type="checkbox"/> The attached application, or</p> <p><input type="checkbox"/> United States application or PCT international application number _____ filed on _____</p> <p>The above-identified application was made or authorized to be made by me.</p> <p>I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.</p> <p>I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. § 1001 by fine or imprisonment of not more than five (5) years, or both.</p>		
<p>WHEREAS, I, the below-identified Inventor, have invented certain new and useful improvements in the Invention identified above and described in the above-identified patent application(s) and/or patent(s) (hereinafter "Invention");</p> <p>WHEREAS, <u>THREEBOND CO., LTD.</u>, (hereinafter "Assignee") having place of business at: <u>Tokyo, Japan</u>, is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent that may be granted therefore in the United States or its territorial possessions and in any and all foreign countries;</p> <p>NOW, this indenture witnesseth, that in consideration of the sum of ONE DOLLAR (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration;</p> <p>I hereby assign, sell and transfer my above-identified rights, title and interest in said Invention, said application(s) as identified above, including any divisions, continuations, and continuations-in-part thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said Invention, and in and to any and all reissues and reexaminations thereof, which may be granted or have granted for said Invention, and in and to any and all priority rights, Convention rights, and other benefits accruing or to accrue to us with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, unto said Assignee;</p> <p>And I hereby authorize and request the Commissioner of Patents and Trademarks to issue any United States Letters Patent which may issue for said Invention to said Assignee, as assignee of the whole right, title and interest thereto;</p> <p>And I further agree to sign and execute all necessary and lawful future documents, including applications for foreign patents, for filing divisions, continuations and continuations-in-part of said application for patent and/or for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid Invention, as the Assignee or its successors and designees may from time to time require and prepare at its own expense.</p> <p>The undersigned hereby grants the firm of <u>LUCAS &amp; MERCANTI, LLP</u>, located at 30 Broad Street, New York, New York, 10004, the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent Office for recordation of this document.</p>		
<b>LEGAL NAME OF INVENTOR</b>	Inventor: <u>Satoru ENDO</u> Signature: <u>Satoru Endo</u>	Date: <u>10/06/2020</u>

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<b>LEGAL NAME OF INVENTOR</b>	Inventor: <u>Hitoshi MAFUNE</u> Signature: <u>島本 仁志</u>	Date: <u>Oct. 5th, 2020</u>

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<b>LEGAL NAME OF INVENTOR</b>	Inventor: <u>Takashi SUZUKI</u> Signature: <u>Takashi Suzuki</u>	Date: <u>10/06/2020</u>

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